

A 1-Watt, 6-Gigahertz IMPATT Amplifier for Short-Haul Radio Applications

By J. E. MORRIS and J. W. GEWARTOWSKI

(Manuscript received September 14, 1973)

A 1-watt IMPATT diode amplifier has been developed for short-haul FM radio relay applications in the 6-GHz common-carrier band. The amplifier is used in the new TM-2 system and as part of a retrofit package to upgrade the performance of the existing TM-1 system. Amplification is provided by a single silicon IMPATT diode which is used in an injection-locked mode. A finned heat sink provides IMPATT diode cooling by natural air convection within the radio bay. The diode is expected to have a mean life greater than 10 years, and it can be replaced in the field without the use of special tools or equipment. This microwave-integrated amplifier contains the rf samplers and detectors necessary to monitor both input and output rf power levels. The input power monitor also provides an input to a power-supply squelch circuit that removes dc power from the IMPATT diode if the rf input signal level becomes too low for adequate performance. The influence of the system requirements upon the amplifier design is described, and data on system performance are presented.

I. INTRODUCTION

The IMPATT diode has been developed to the point where several watts of cw power can be generated reliably in the microwave frequency range. This negative-resistance device used in conjunction with a circulator comprises a reflection amplifier suitable as the power amplifier in a microwave communications transmitter. In the present application, the diode operates in the injection-locked oscillator mode. It was demonstrated by Tatsuguchi, Dietrich, and Swan that such an amplifier using a single silicon IMPATT diode could meet the basic performance objectives of a typical short-haul radio-relay system.¹ The amplifier operates with a nominal gain of 20 dB and a noise figure of less than 52 dB. The corresponding system performance is better than 22 dBnc0 per hop for a 1200-circuit message load. The amplifier's system performance is found to be dominated by thermal noise, with intermodulation distortion negligible. The dc-to-rf efficiency is 4 percent.

To be useful to the system, the amplifier package also contains rf samplers and detectors necessary to monitor the rf input and output power levels. The input power-monitor circuit furnishes the input information for a power-supply squelch circuit. If the input rf level drops low enough so that the locking bandwidth of the amplifier becomes small, the power supply is turned off, preventing the IMPATT oscillator from free-running out of the assigned frequency range. The dc power is automatically restored when the input rf level returns to normal. The amplifier also contains harmonic suppression filters to prevent radiation of spurious tones. The amplifier has standard WR-159 waveguide input and output ports with vswrs of less than 1.07 across the band.

To be suitable for manufacture, an economical design was evolved based on the microwave integrated-circuit techniques successfully employed in the TH-3 system by Dietrich.² The construction consists of a thin-film strip-line pattern on a suspended alumina substrate, which is mounted in a die-cast aluminum housing, connected to a coaxial section containing the IMPATT diode, the tuning mechanism, and a second harmonic filter. In addition, a wide range of tunability had to be incorporated to accommodate a wide range of diode parameters, both for initial manufacture and field replacement of the diode. Both frequency and output power adjustments are provided. All these features have been successfully accomplished in the amplifier designed for manufacture.

II. AMPLIFIER DESIGN

The amplifier design is based upon the use of a single silicon IMPATT diode used in a phase-locked oscillator mode. This mode of operation, described below, is chosen since it permits the relatively high gain of approximately 20 dB to be obtained stably in a single stage.

2.1 Operating point selection

The choice of an operating point for the amplifier follows the method described by Tatsuguchi et al.¹ Figure 1 illustrates typical contours of constant system thermal noise performance, in dBm/Hz per hop, plotted on coordinates of amplifier output power versus amplifier noise figure. The system performance contours shown apply to the highest frequency message slot of one particular short-haul FM system configuration that is operated at a 1200-message circuit loading. The contours assume that a +10-dBm level signal is available to drive the amplifier. This input power level is the minimum value anticipated in one of the systems in which this amplifier will be used. The options open to the amplifier circuit designer are illustrated on the same figure

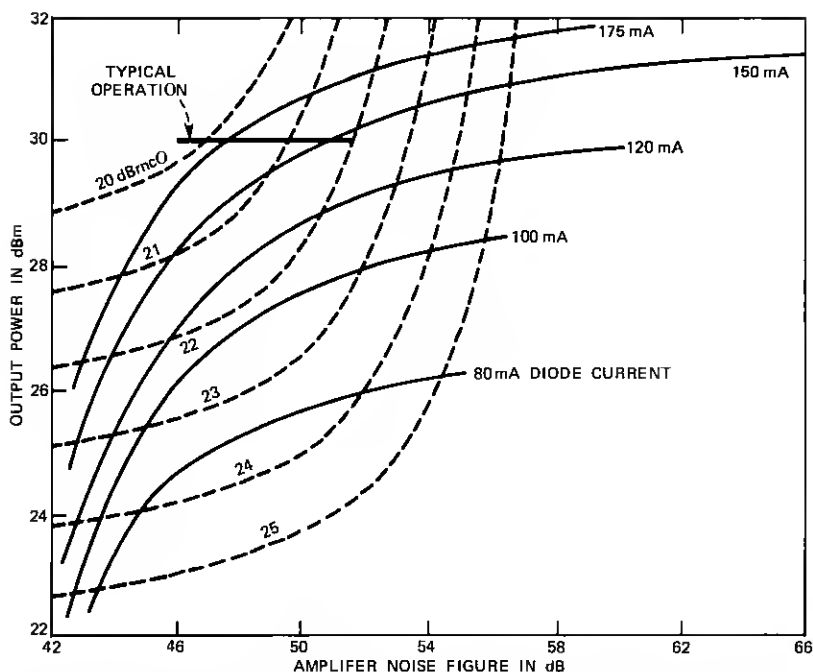


Fig. 1—Contours of constant system thermal-noise performance, in dBnc0 per hop, plotted on coordinates of amplifier output power versus amplifier noise figure. A particular amplifier's performance is indicated by the solid lines at several IMPATT diode dc currents. Typical performance obtained on a large sample of amplifiers when adjusted for 1-watt output power is shown.

by the superimposed contours of IMPATT amplifier performance at various dc power levels. For a given dc power level, the operating point is a function of the microwave circuit impedance seen by the IMPATT device. The shape of these curves is due to the fact that an IMPATT device becomes noisier as the rf level is increased. From such curves, it becomes apparent that operation at the maximum possible rf power will result in poor system performance. Optimum performance occurs at neither maximum rf power nor minimum noise. It is instructive to note that the optimum performance, i.e., lowest dBnc0 number, occurs with the largest dc power. The use of high dc powers must be tempered by reliability considerations, which generally dictate the use of lower powers.

For this amplifier application, the trade-off between rf output power, FM noise, and diode reliability formed the basis of the decision to operate at 1-watt rf output with 24 watts of dc supplied to the IMPATT diode. At this operating point, the diode junction temperature is expected to be approximately 200°C in convection-cooled radio bays

operating in room ambient temperature up to 50°C. This operating point is expected to provide a mean diode life greater than 10 years. This reliability is the result of careful device processing combined with low thermal impedances both within the diode package and between the diode case and ambient air.

2.2 Oscillator mode

The IMPATT diode is operated in an injection-locked (phase-locked) oscillator mode, shown schematically in Fig. 2. The IMPATT device and its associated resonating circuitry terminate one port of a circulator in a negative impedance. In the absence of an input signal, a free-running oscillation at frequency f_0 occurs, which is coupled to the output through the circulator. When an appropriate input signal is added, the oscillation frequency locks to the input over a band of frequencies $2\Delta f$, approximately symmetrical about f_0 . The free-running frequency is adjusted to the desired operating channel. Figure 2 illustrates the power and phase variations that occur across the locking frequency band. The power levels and oscillator external Q (Q_{ex}) are chosen such that Δf is at least 10 times the highest modulating frequency. In this way, only the center linear portion of the phase variation curve is used, and phase distortion is minimized.

Since the rf output power is fixed from other considerations (system performance and fading margin) and the rf input power available in

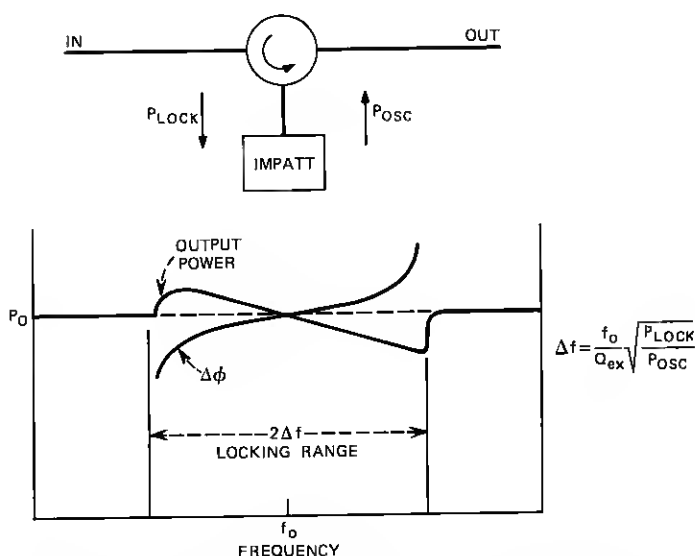


Fig. 2—Simplified representation of an injection-locked oscillator.

the systems in which the amplifier is to be used is limited, the designer is required to provide a circuit of the lowest possible Q . For this amplifier, a low Q circuit is provided by the use of a diode circuit consisting of a coaxial one-quarter-wavelength transformer plus a short section of coaxial line between the transformer and the diode that series-tunes the IMPATT diode's capacitance. With this resonator, the circuit Q is sufficiently low that Q_{ez} is largely determined by the IMPATT device itself.

2.3 IMPATT characteristics

The IMPATT diode used for this amplifier is an n-type silicon diode whose junction side is bonded to a metallized diamond within a copper and ceramic microwave pill package.³ The large-signal rf characteristics of the diodes are measured near 6 GHz using the method described by Decker et al.⁴ The diode wafer admittance is measured on all devices at 24-watts dc, with an rf voltage corresponding to the diode's operating point in the amplifier. Wafer susceptances are specified at 19.0 millimhos. Tuning is provided to accommodate a range of diode susceptances. The wafer Q , defined as the magnitude of the ratio of wafer susceptance to wafer conductance, has values that vary by a factor of 2.5 to 1.

2.4 Circuit description

The requirements of practical radio-relay equipment dictate an amplifier circuit somewhat more complex than the simple circulator, diode, and resonator shown in Fig. 2. A more complete schematic of the amplifier is shown in Fig. 3. The circuit contains three circulators, of which the center circulator corresponds to the one shown in Fig. 2. Additional circulators with one port resistively terminated are used at both the amplifier's input and output to provide isolation from the effects of external reflections and to provide input and output return losses better than 30 dB.

The dc power for the IMPATT diode from the current-regulated power supply is coupled to the oscillator port of the center circulator through a resistor and a band-stop filter tuned to 6 GHz. The resistor is used here to provide the high resistive impedance at low frequencies that has been shown by Brackett to prevent spurious oscillations.⁵ The dc power is isolated from the remaining rf circuit by a series capacitor in the main rf circuit adjacent to the band-stop filter.

On the output side of the center circulator, a small sample of the amplified output is picked off by a nondirectional coupling probe. This sample of the rf output is detected using a point contact diode

grated circuits (FICS) consisting of patterns defined photolithographically on 0.024-inch (0.61-mm) thick unglazed alumina are used as a suspended-substrate strip-line transmission-line medium. The strip-line circuitry, as well as the amplifier's waveguide input and output, are contained in a die-cast aluminum housing, shown in the amplifier photograph, Fig. 4. The IMPATT diode and its resonator are contained in a short section of coaxial line that projects perpendicularly from the housing and is topped by the large, finned heat sink used for IMPATT diode cooling. Adjustments are provided on the coaxial section for field tuning of frequency and power output.

3.1 Strip-line circuits

The layout of the circuitry within the die-cast housing is illustrated in Fig. 5 and shown pictorially in Fig. 6. The ceramic substrates are located within a narrow channel to avoid multimoding problems. The complex substrate shape is fabricated by an automated laser-cutting



Fig. 4—Complete amplifier.

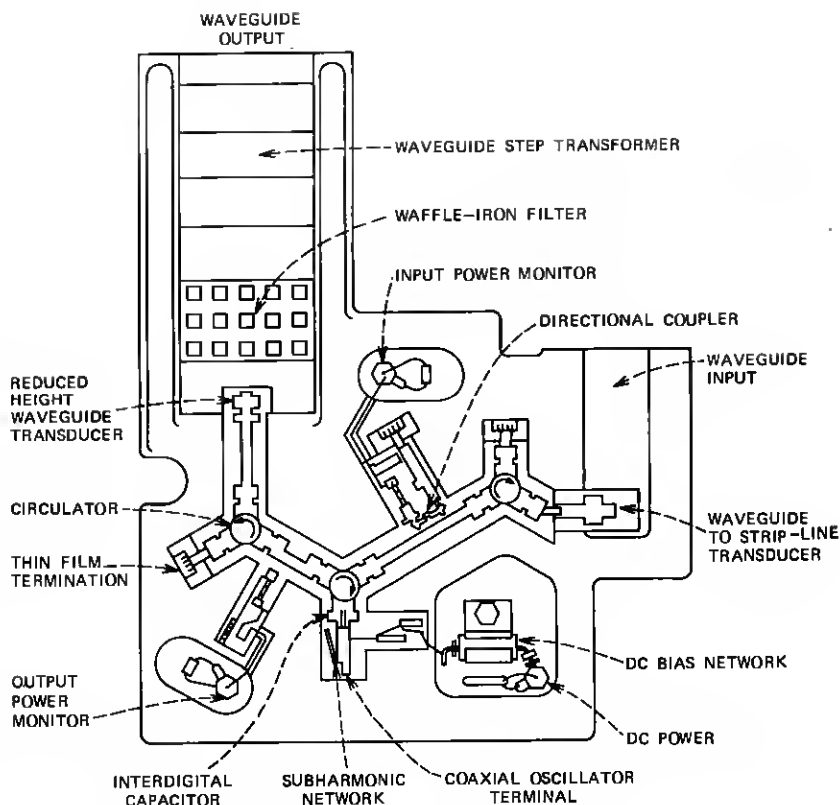


Fig. 5—Arrangement of waveguide and strip-line circuit within die-cast housing.

technique.⁶ The amplifier's full-height waveguide input is shown on the right. A thin-film probe transition from the input waveguide to the suspended-substrate strip-line couples the input signal to the first of the three circulators. This circulator, with one port terminated in a thin-film resistor, provides the necessary input isolation. The circulator and termination designs follow closely those described by Dietrich,² modified to improve the temperature stability. A directional coupler, located between the input and center circulators, diverts approximately 10 percent of the input rf signal to the input detector diode to generate the dc needed for hay panel metering and power-supply squelch functions.

The remaining input signal is coupled to the oscillator port of the center circulator. The series capacitor, which dc-isolates this port, is realized by a narrow, meandering, interdigital gap in the thin-film conductor. The 6-GHz hand-stop bias filter is realized by a high-

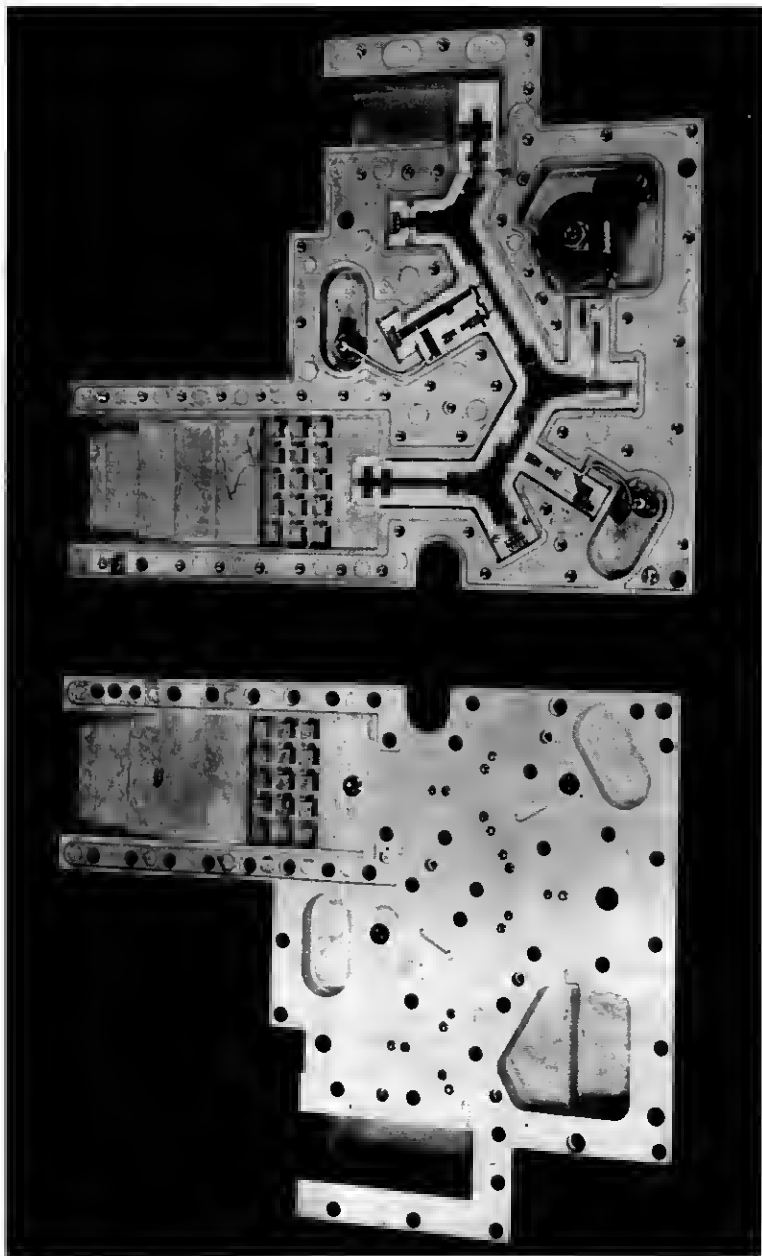


Fig. 6—Pictorial view of open die-casting showing strip-line circuitry.

characteristic-impedance line along which, at quarter-wavelength intervals, are placed two quarter-wavelength-long open-circuited stubs of lower characteristic impedance. The bias circuit is completed by a 47-ohm power resistor that is clamped to the aluminum housing to maximize heat transfer. Several ferrite heads are placed on the leads of this resistor to provide additional stability against bias circuit oscillations.

An open-circuited stub, one-half-wavelength long at 6 GHz, which connects to the oscillator terminal through a thin-film resistor, is used to control the circuit impedance at 3 GHz (the subharmonic of the 6-GHz band) without adding significant loss or mismatch at 6 GHz.⁷ This was found to be necessary to eliminate frequency jumps during tuning, which occur when the subharmonic impedance is too high.

At the end of the thin-film pattern (coaxial oscillator terminal), connection is made, using a bellows, to the center conductor of the coaxial line through the top half of the aluminum housing.

The amplified rf signal reflected from the IMPATT diode down the coaxial line is coupled by the center circulator to the output circulator. A small portion of the amplified output is capacitively coupled to the output detector circuit to provide the direct current for ray panel metering and alarm functions. This nondirectional coupling is approximately 28 dB. The amplified signal passes through the output circulator, used as an isolator, and is coupled into a reduced-height waveguide. Within the reduced-height waveguide, a waffle-iron filter⁸ having a low-pass characteristic strips the amplified signal of any residual harmonic energy either generated by the IMPATT or contained in the input signal. Following the waffle-iron filter, a four-step transition couples the reduced-height waveguide to standard-height WR-159 waveguide.

3.2 Coaxial circuit

A cross section of the coaxial line is shown in Fig. 7. At the bottom, just above the bellows contact to the thin-film circuit, is located a three-resonator, radial-line, band-stop filter⁹ that is tuned to the 12-GHz second harmonic of the 6-GHz common-carrier band. The filter prevents the second harmonic energy generated by the IMPATT diode from causing anomalous monitor circuit operation. Appropriate steps in the coaxial center conductor in the filter section provide a good match across the 6-GHz band. The center conductor tip is spring-loaded against the IMPATT diode, which is held centered at the upper end of the coaxial section. A large, finned heat sink contacting

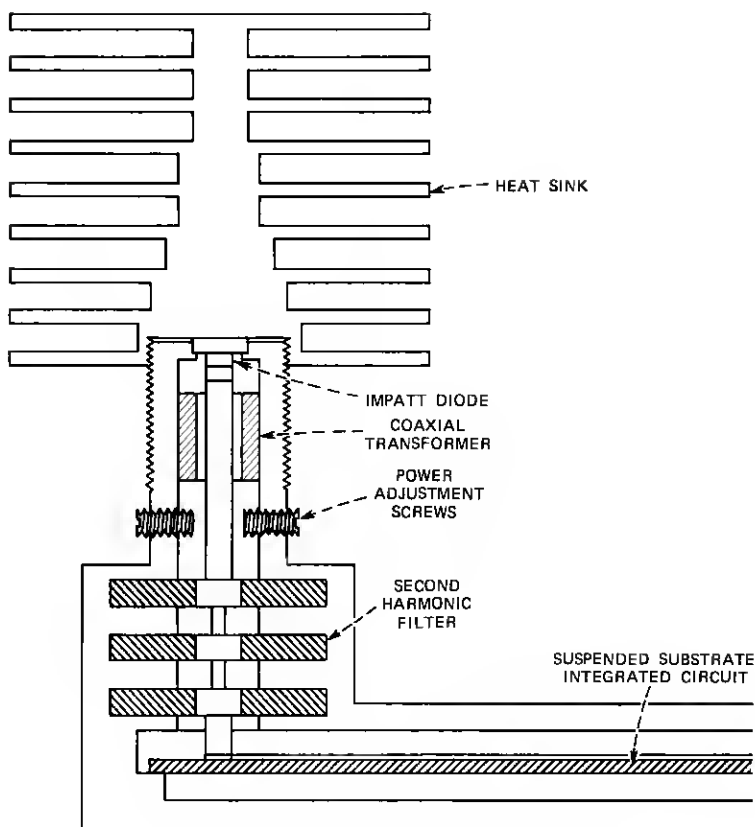


Fig. 7—Cross section of the coaxial line section.

the back of the diode provides diode cooling and eliminates the need for forced convection.

IMPATT tuning is accomplished by a movable quarter-wavelength coaxial transformer and four capacitive power-adjustment screws located radially around the coaxial line at a point nominally an eighth-wavelength from the end of the transformer. The position of the transformer relative to the IMPATT diode primarily determines the frequency of operation. The transformer is moved using a large-diameter knurled ring, shown just below the heat sink in Fig. 4. This ring is mechanically coupled to the transformer through two slots in the coaxial line. These slots are completely covered by the transformer and ring to prevent rf leakage.

The transformer section characteristic impedance is designed to produce 1 watt at the amplifier's output port (nearly 1 dB more at the

diode's location) with the highest Q diode and with the power adjustment screws adjusted flush with the inner diameter of the coaxial outer conductor. For all other diodes that would give greater than 1 watt with this transformer, capacitance is added using the four power-adjustment tuning screws. When transformed through the coaxial circuit to the diode position, the added capacitance appears as an increase in the resistive part of the circuit impedance. Increased circuit resistance reduces the generated power down to the 1-watt level, where optimum system performance occurs. This power adjustment is made on diodes having low values of Q ; the increase in circuit Q because of the screw insertion is counterbalanced by the lower diode Q , so that the overall external Q is not increased by this power adjustment when compared with high Q diodes requiring little screw penetration.

3.3 Circuit tuning

The circuitry within the die-cast housing is initially tuned in the factory with a 7-mm precision connector located in place of the IMPATT diode and heat sink. During the initial tuning, the transformer is not installed and the power-adjustment screws are adjusted flush with the coaxial-line inner surface. Tuning of all ports of the three circulators to better than 30-dB return loss is accomplished across the 8-percent common-carrier band. The three ports of the center circulator are tuned over a slightly wider band to include the extremities of the locking bandwidth of amplifiers operated on the end channels of the common-carrier band.

By matching the diode port of the center circulator to achieve this broadband high return loss, the oscillator circuit Q is essentially determined by that of the quarter-wavelength transformer and the short section of 50-ohm line from the transformer to the diode. In practice, Q_{ex} of the oscillator is determined largely by the IMPATT diode wafer. The transformer position and power adjustment screws permit adjustment in the field of any amplifier to 1 watt on any channel assignment with any diode. The IMPATT diode is replaceable in the field by simply removing the heat sink and inserting a new diode in the coaxial line against the spring-loaded center conductor.

The amplifier cost has been kept low by the use of thin-film integration, casting technology, and laser cutting of ceramic substrates.

IV. AMPLIFIER PERFORMANCE

Ten models were constructed in the laboratory, and information was conveyed to the Western Electric Company, who is now producing the unit. Measurements of intermodulation distortion indicate that the distortion products are small and that system performance

can be accurately predicted on the basis of power output and FM thermal noise with no correction for distortion. Performance shown in Fig. 1 can be readily obtained using the silicon IMPATT diodes in manufacture. A detailed evaluation has been completed of a TM-2 system in Ohio that includes eight factory-built IMPATT amplifiers. Satisfactory operation was noted over a 10-month test period.

V. SUMMARY

A 1-watt, 6-GHz silicon IMPATT diode amplifier has been developed and is being manufactured for use as the transmitter power amplifier in short-haul radio systems. The amplifier operates with a nominal gain of 20 dB and a noise figure of less than 52 dB. The noise contribution of the IMPATT amplifier is substantially thermal noise, with intermodulation distortion negligible. The dc-to-rf efficiency is 4 percent. The amplifier includes integrated input and output rf power monitors and harmonic suppression circuitry.

The input monitor circuit furnishes the input information for the power-supply squelch circuit. If the input rf level drops low enough so that the locking bandwidth becomes small, the power supply is turned off, preventing the oscillator from free-running out of the assigned frequency range. The dc power is automatically restored when the input level returns to normal.

The low cost and reliability of this IMPATT amplifier make it an attractive rf output device in short-haul applications.

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